



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 159 FR4 60 L41.70 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_159_FR4_60_L41.70_p18_10

Layers	in μ	Material	Build-Up	Assembly
Layer-1	60 μ	Copper		A1 B
	100 μ	Prepreg	(100 μ PrePreg-Type: 2125)	
	180 μ	Prepreg	(180 μ PrePreg-Type: 7628)	
	180 μ	Prepreg		
Layer-2	70 μ	Copper		
	410 μ	L-FR4		
Layer-3	70 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	60 μ	Copper		

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